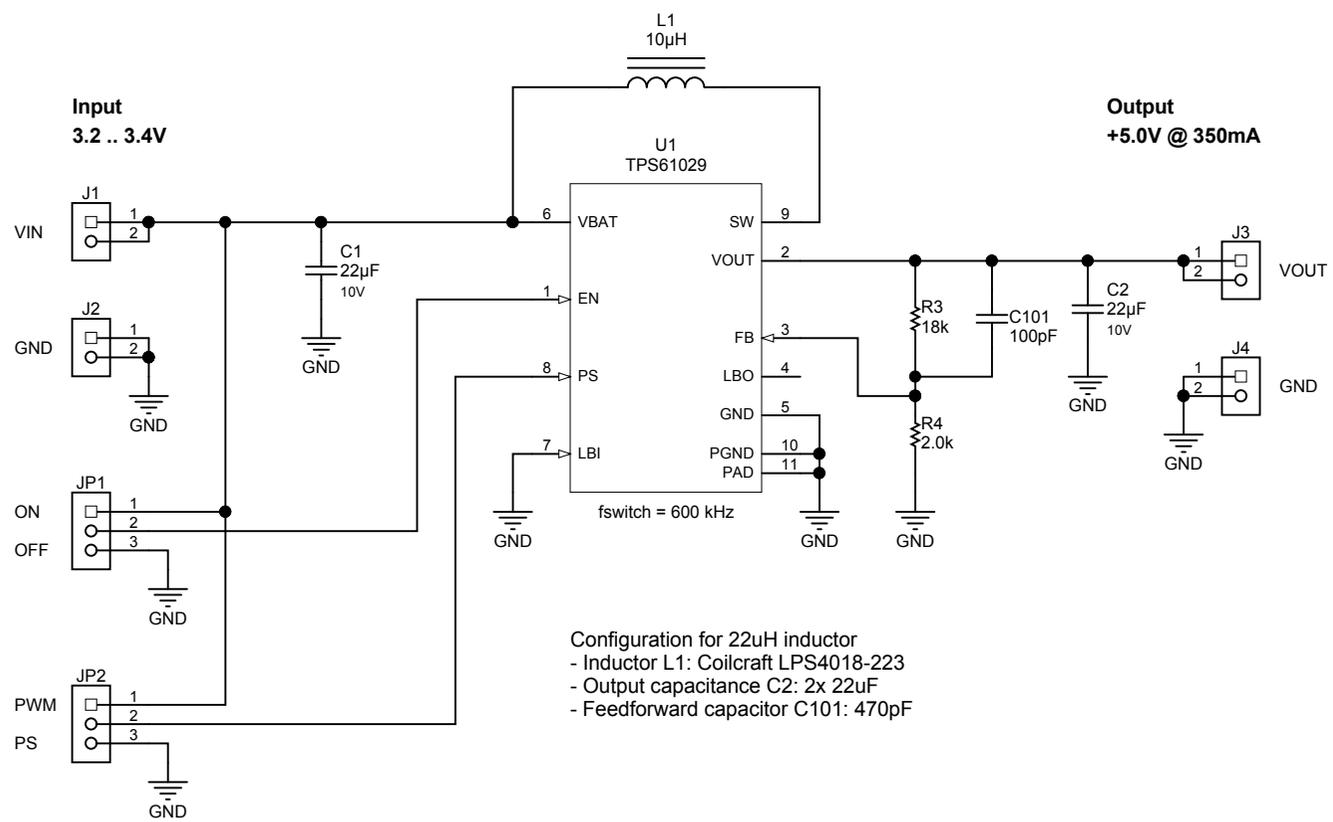


Revision History	
Revision	Notes
A	* Built & Tested



Configuration for 22µH inductor
 - Inductor L1: Coilcraft LPS4018-223
 - Output capacitance C2: 2x 22µF
 - Feedforward capacitor C101: 470pF

Design Notes

- * Parts with RefDes > 100 have no footprint on PCB
- * Modified TPS61020EVM

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Number: PMP30003 Rev: A
 SVN Rev: Version control disabled
 Drawn By:
 Engineer: Matthias Ulmann

Designed for: Public Release Mod. Date: 1/14/2016
 Project Title: Automotive Boost
 Sheet Title:
 Assembly Variant: [No Variations] Sheet: 1 of 1
 File: PMP30003RevA.SchDoc Size: A4
 Contact: <http://www.ti.com/support>



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